

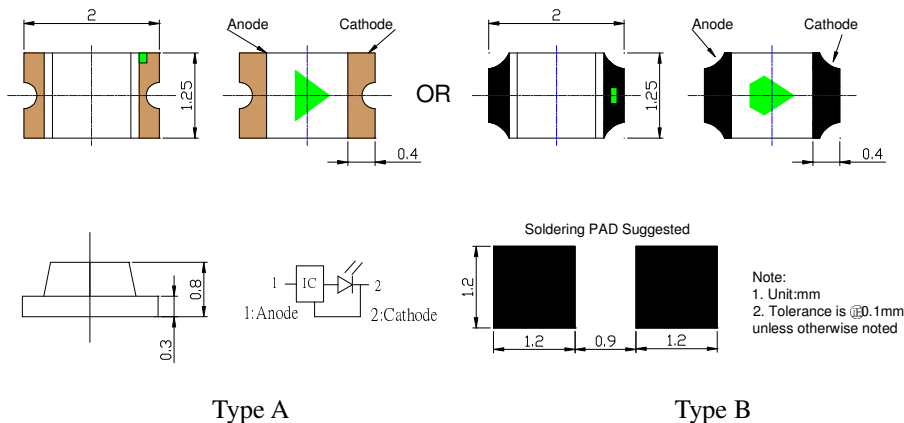
■Features

- Single chip Flashing Type
- 2.0x1.25x0.8mm(0805) standard package.
- Suitable for all SMT assembly methods.
- Compatible with infrared and vapor phase reflow solder process.
- This product doesn't contain restriction Substance, comply ROHS standard.
- Compatible with automatic placement equipment.

■Applications

- Automotive : Dashboards, stop lamps, turn signals.
- Backlighting : LCDs, Key pads advertising.

■Outline Dimension



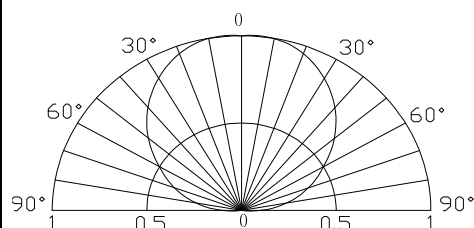
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value	Unit
DC Forward Current	I _F	30	mA
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40~ +85	°C
Lead Soldering Temperature	Tsol	260°C/10sec	-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

Part Number	Color		V _F (V)			Fled (Hz)	I _v (mcd)			λD(nm)			2θ1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			I _F =20mA										
OSWS0805C1E	White	W	3.0	3.5	4.0	1.5	350	450	550	CCT: 7000-20000K			120
OSKS0805C1E	Pink	K	3.0	3.5	4.0	1.5	150	200	250	X:0.36~0.40, Y:0.12~0.20			120
OSBS0805C1E	Blue	B	3.0	3.5	4.0	1.5	30	50	70	460	465	475	120
OSPS0805C1E	True Green	PG	3.0	3.5	4.0	1.5	400	550	700	520	525	530	120
OSGS0805C1E	Yellow Green	YG	3.0	3.5	4.0	1.5	25	35	50	565	570	575	120
OSYS0805C1E	Yellow	Y	3.0	3.5	4.0	1.5	70	100	150	585	590	595	120
OSOS0805C1E	Orange	O	3.0	3.5	4.0	1.5	70	100	150	600	605	610	120
OSRS0805C1E	Red	R	3.0	3.5	4.0	1.5	70	100	150	620	625	630	120

Note: *1 Tolerance of measurements of chromaticity coordinate is ±10%

*2 Tolerance of measurements of dominant wavelength is ±1nm

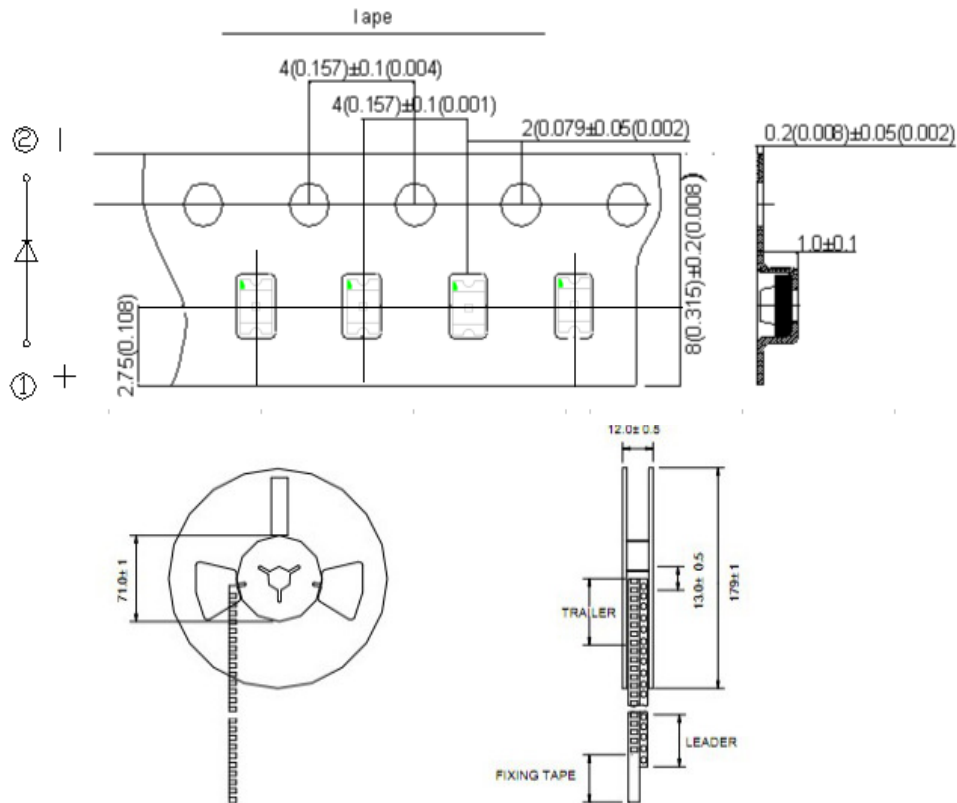
*3 Tolerance of measurements of luminous intensity is ±15%

*4 Tolerance of measurements of forward voltage is±0.1V

*5. Tolerance of measurements of Frequency is ±20%

■ **Taping and Orientation.**

1. Quantity:3000pcs/Reel
2. Note: The tolerances unless mentioned is ± 0.1 mm,Unit:mm



■ **Cautions:**

1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
2. Heat generation must be taken into design consideration when using the LED.
3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.